



FCX1151A

-40V PNP POWER TRANSISTOR IN SOT89

Features

- BV_{CEO} > -40V
- I_C = -3A High Continuous Current
- I_{CM} = -5A Peak Pulse Current
- Very Low V_{CE(sat)} < -220mV at -1A
- R_{CE(sat)} = 66mΩ at -3A
- P_D = 2W
- Complimentary Part FCX1051A
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

Applications

- Motor Driving (Including DC Fans)
- Solenoid, Relay and Actuator Drivers
- DC-DC Modules
- Backlight Inverters
- Power Switches
- MOSFET Gate Drivers

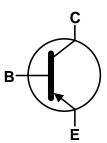
Mechanical Data

Case: SOT89

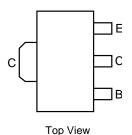
- Case Material: Molded Plastic, "Green" Molding Compound UL Flammability Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin Plated Leads. Solderable per MIL-STD-202, Method 208 ³
- Weight: 0.052 grams (Approximate)







Device Symbol



Pin-Out

Ordering Information (Note 4)

Part Number	Compliance	Marking	Reel Size (inches)	Tape Width (mm)	Quantity Per Reel
FCX1151ATA	AFC-Q101	151	7	12	1 000

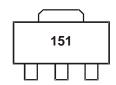
Notes:

1. EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. All applicable RoHS exemptions applied.

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- 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

Marking Information



151 = Product Type Marking Code



Absolute Maximum Ratings (@TA = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V _{CBO}	-45	V
Collector-Emitter Voltage	V _{CEO}	-40	V
Emitter-Base Voltage	V _{EBO}	-5	V
Continuous Collector Current	Ic	-3	Α
Peak Pulse Current	I _{CM}	-5	Α
Base Current	I _B	-500	mA

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit		
	(Note 5)		1		
Power Dissipation	(Note 6)	P_{D}	1.6	W	
	(Note 7)		2.0		
	(Note 5)		125		
Thermal Resistance, Junction to Ambient Air	(Note 6)	$R_{ hetaJA}$	78	°C/W	
	(Note 7)		62.5		
Thermal Resistance, Junction to Lead	(Note 8)	$R_{ heta JL}$	3.6	°C/W	
Operating and Storage Temperature Range	T _{J,} T _{STG}	-55 to +150	°C		

ESD Ratings (Note 9)

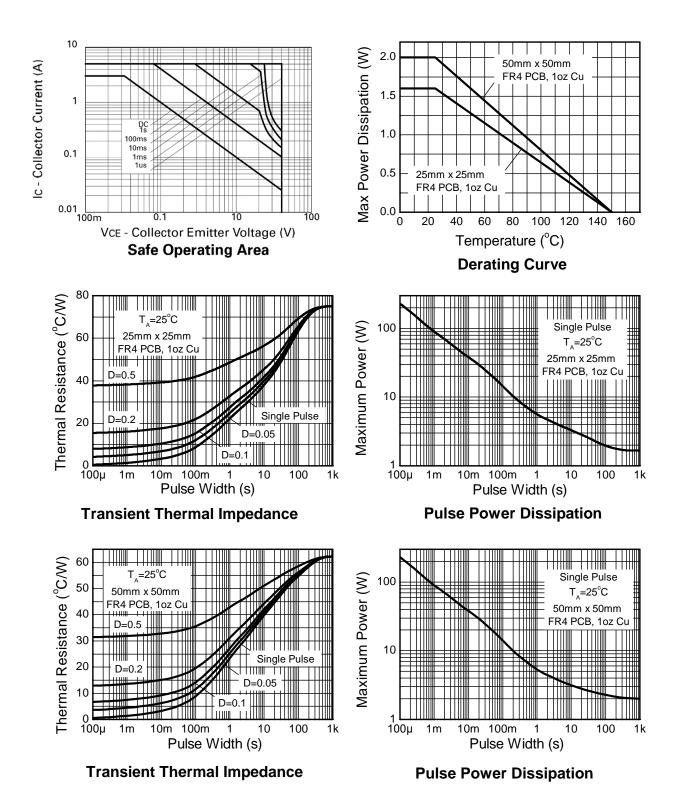
Characteristic	Symbol	Value	Unit	JEDEC Class
Electrostatic Discharge - Human Body Model	ESD HBM	4,000	V	3A
Electrostatic Discharge - Machine Model	ESD MM	400	V	С

Notes:

- 5. For a device mounted with the exposed collector pad on 15mm x 15mm 1oz copper that is on a single-sided 1.6mm FR-4 PCB; device is measured under still air conditions whilst operating in a steady-state.
- 6. Same as Note 5, except the device is mounted on 25mm x 25mm 1oz copper.
- 7. Same as Note 5, except the device is mounted on 50mm x 50mm 1oz copper.
- 8. Thermal resistance from junction to solder-point (on the exposed collector pad).
 9. Refer to JEDEC specification JESD22-A114 and JESD22-A115.

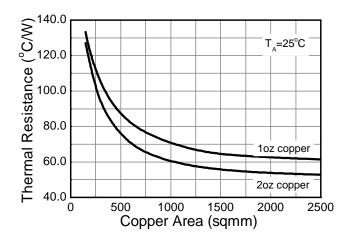


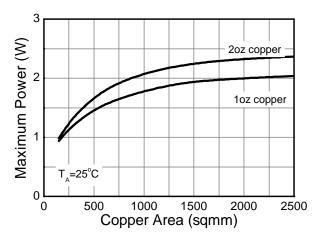
Thermal Characteristics and Derating Information





Thermal Characteristics and Derating Information (Cont.)







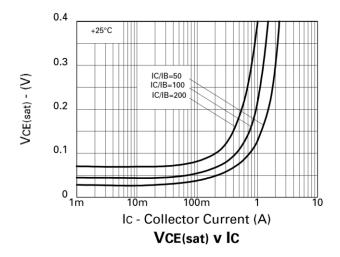
Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

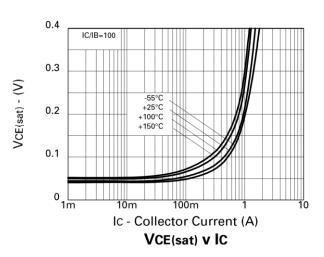
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
Collector-Base Breakdown Voltage	BV _{CBO}	-45	_	_	V	I _C = -100μA
Collector-Emitter Breakdown Voltage	BV _{CES}	-40	_	_	V	I _C = -100μA
Collector-Emitter Breakdown Voltage (Note 10)	BV _{CEO}	-40	_	_	V	I _C = -10mA
Collector-Emitter Breakdown Voltage	BV _{CEV}	-40	_	_	V	$I_C = -100\mu A$, $V_{EB} = 1V$
Emitter-Base Breakdown Voltage	BV _{EBO}	-7	_	_	V	$I_E = -100 \mu A$
Collector Cutoff Current	I _{CBO}	_	-0.3	-100	nA	V _{CB} = -36V
Collector Cutoff Current	I _{CES}	_	-0.3	-100	nA	V _{CES} = -32V
Emitter Cutoff Current	I _{EBO}	_	-0.3	-100	nA	V _{EB} = -4V
DC Current Transfer Static Ratio (Note 10)	h _{FE}	270 250 180 100	450 400 300 190 45	- 800 - - -	_	I_{C} = -10mA, V_{CE} = -2V I_{C} = -0.5A, V_{CE} = -2V I_{C} = -2A, V_{CE} = -2V I_{C} = -3A, V_{CE} = -2V I_{C} = -5A, V_{CE} = -2V
Collector-Emitter Saturation Voltage (Note 10)	VCE(sat)	_	-60 -120 -140 -200	-90 -180 -220 -300	mV	$I_C = -0.1A$, $I_B = -1mA$ $I_C = -0.5A$, $I_B = -5mA$ $I_C = -1A$, $I_B = -20mA$ $I_C = -3A$, $I_B = -250mA$
Base-Emitter Saturation Voltage (Note 10)	V _{BE(sat)}	_	-985	-1050	mV	$I_C = -3A$, $I_B = -250mA$
Base-Emitter Turn-on Voltage (Note 10)	V _{BE(on)}	_	-850	-950	mV	$I_C = -3A$, $V_{CE} = -2V$
Transitional Frequency	f⊤	_	145	_	MHz	I _C = -50mA, V _{CE} = -10V, f = 50MHz
Output Capacitance	C _{obo}		40	_	pF	V _{CB} = -10V, f = 1MHz
Switching Time	t _{on}	_	170	_	ns	$V_{CC} = -30V, I_{C} = -2A,$
Switching fille	t _{off}	_	460	_	ns	$I_{B1} = I_{B2} = \pm 20 \text{mA}$

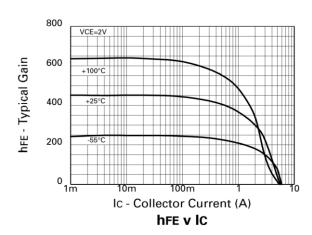
Note: 10. Measured under pulsed conditions. Pulse width = 300μ s. Duty cycle $\leq 2\%$.

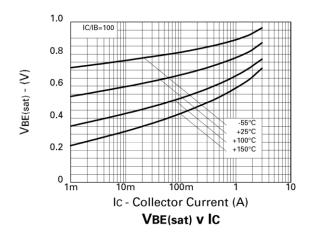


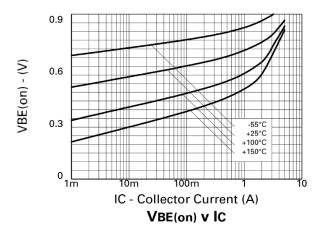
Typical Electrical Characteristics ($@T_A = +25^{\circ}C$, unless otherwise specified.)









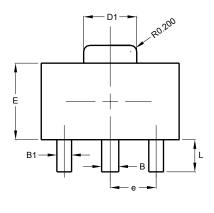


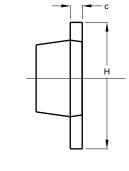


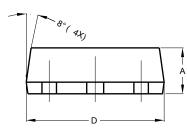
Package Outline Dimensions

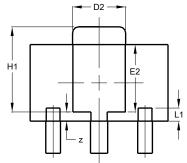
Please see http://www.diodes.com/package-outlines.html for the latest version.

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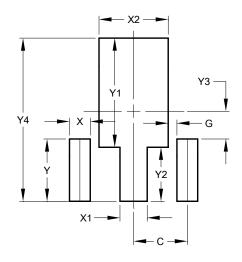


SOT89						
Dim	Min	Max	Тур			
Α	1.40	1.60	1.50			
В	0.50	0.62	0.56			
B1	0.42	0.54	0.48			
С	0.35	0.43	0.38			
D	4.40	4.60	4.50			
D1	1.62	1.83	1.733			
D2	1.61	1.81	1.71			
Е	2.40	2.60	2.50			
E2	2.05	2.35	2.20			
е	1	-	1.50			
Н	3.95	4.25	4.10			
H1	2.63	2.93	2.78			
L	0.90	1.20	1.05			
L1	0.327	0.527	0.427			
z 0.20 0.40 0.30						
All Dimensions in mm						

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

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Dimensions	Value
פווטופווזטווט	(in mm)
C	1.500
G	0.244
Х	0.580
X1	0.760
X2	1.933
Υ	1.730
Y1	3.030
Y2	1.500
Y3	0.770
Y4	4.530



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